

PACKING BODY OF SENSOR AND ITS USING METHOD

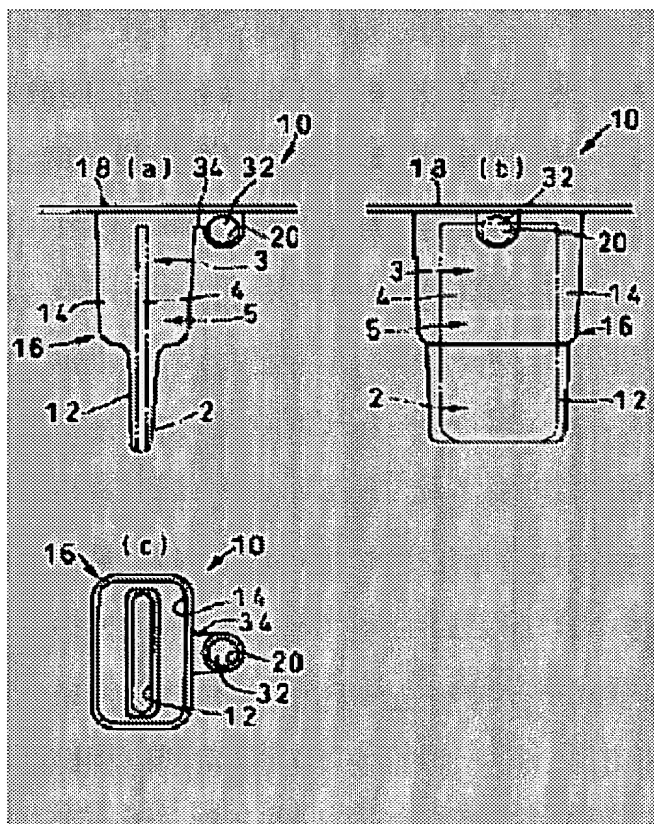
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Abstract of JP2000314711

PROBLEM TO BE SOLVED: To provide a packing body whose handling performance is excellent even if a sensor is downsized and whose storage performance is excellent.

SOLUTION: This is a packing body 10 which stores and packs a sensor 5 in which a sensor part 2 and a connector part 3 are respectively formed at one end and the other end of a substrate. The packing body 10 is equipped with a packing body main body 16 having a sensor holding part 12 which has a bottom and at least stores and holds the sensor part 2 of the sensor 5 and a connector storing part 14 which has an opening cross section larger than that when connected to a sensor holding part 12 and accommodates a connector part 3, and a cover 18 which can close an opening of the connector storing part 14.



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[Claim 6] The packing body for sensor according to claim 2, wherein the cover member is formed of a transparent material or a material on which a sensor removal position is printed.